# **Specifications for Approval**

Customer :\_\_\_\_\_

Model name : GG0804A1FSN6G REV: A

Description : LCM (G0804A1FSN6-DB016-010820)

ISSUE	ENG	QA	APPROVAL

Customer Approval	Accept Reject Comment:
	Approved by:

## REVISION RECORD ( MODEL NO. : GG0804A1FSN6G )

Revision	Revision	Date	Page	Contents
А	2001/8/	/27		Initial Release



- **\* CONTENTS**
- 1. FEATURES
- 2. MECHANICAL SPECIFICATIONS
- **3. ELECTRICAL SPECIFICATIONS**
- 4. POWER SUPPLY
- 5. ELECTRO-OPTICAL CHARACTERISTICS
- 6. TERMINAL PIN FUNCTION AND BLOCK DIAGRAM
- 7. AC CHARACTERISTICS
- 8. INSTRUCTION DESCRIPTION
- 9. QUALITY SPECIFICATIONS
- **10. RELIABILITY**
- 11. HANDLING PRECAUTIONS
- **12. OUTLINE DIMENSION** 
  - . X ANNEX : 1. SAMPLES OUTGOING INSPECTION REPORT
    - 2. DEFINITION OF LCM SERIES NUMBER
    - 3. REVISION RECORD

MODEL	GG0804A1FSN6G	1/18	PRODUCT SPECIFICATIONS	REV: A

Goldentek Display System Co., Ltd

#### **1. FEATURES**

The features of LCD are as follows

* Display mode	: FSTN, Positive, Transflective
* Color	: Display dot : Black
	Background: White
* Display Format	: 84(W) X 48(H) Dots
* IC	: PCD8544
* Interface Input Data	: Serial data interface form a MPU
* Driving Method	: 1/48 Duty, 1/7 Bias
* Viewing Direction	: 6 O'clock

#### 2. MECHANICAL SPECIFICATIONS

ltem	Specification	Unit
Module Size	38.36(W) x 33(H) x 2.0(T)	mm
Number of dots	84(W) x 48(H)	-
Viewing Area	34.96(W) x 23.4(H)	mm
Effective display area	28.95(W) x19.41(H)	mm
Dot Size	0.315(W) x 0.375(H)	mm
Dot Pitch	0.345(W) x 0.405(H)	mm

#### **3. ELECTRICAL SPECIFICATIONS**

3-1. Absolute Maximum Ratings (Ta=25°C)

ltom	Symbol	Sta			
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	V <sub>DD</sub>	-0.5	-	7	V
Supply Voltage For LCD Drive	$V_0 - V_{SS}$	-0.5	-	10	V
Input Voltage	VI	-0.5	-	V <sub>DD</sub> +0.5	V
Ground supply current	I <sub>SS</sub>	-0.5	-	50	mA
DC input or output current	I <sub>I</sub> I <sub>O</sub>	-10	-	10	mA
Total power dissipation	P <sub>TOT</sub>	-	-	300	mA
Operating temperature	T <sub>op</sub>	-20	-	70	°C
Storage temperature	T <sub>STG</sub>	-30	-	80	°C

MODEL	GG0804A1FSN6G	2/18	PRODUCT SPECIFICATIONS	REV: A

## 3. ELECTRICAL SPECIFICATIONS (Continued)

3-2. Electrical Characteristics (Vss=0V)

ltem		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply Voltage		Vdd	-	2.7	-	3.3	V
	"H" Level	V <sub>IH</sub>		$0.7V_{DD}$	-	Vdd	V
Input Voltage	"L" Level	VIL	VDD-2.0V	$V_{SS}$	-	0.3Vdd	V
			VDD =2.85V				
Current Cons	sumption	I <sub>DD</sub>	test pattern = notel	-	6.20	7.4	mA
LCD Drive Voltage (Recommended Voltage)		Vout	Ta =25℃	7.3	7.6	7.9	V

Note:

- 1) TEST PATTERN: ALL DOTS ON STATES .
- 2) DUTY = 1/48

3) ELECTRONIC VOLUME REGISTER (VOP 6:0)= 1000101B RECOMMANDABLE.

\* OPERATIONG VOLTAGE FLUCATUATE ABOT <u>+</u> 0.3V BY EACHPANEL.

MODEL GG0804A1FSN6G 3/18 PRODUCT SPECIFICA	ONS REV: A
--	------------



Item	Symbol	Temp.	Min.	Тур.	Max.	Unit	Conditions	Note
Viewing	$\Theta 2 - \Theta 1$	<b>25℃</b>	30	-	-	Deg	Cr > 2	1 0
Angle	Φ	230	80	-	-	Deg.	01 <u>-</u> 2	1,2
Contrast Ratio	Cr	<b>25</b> ℃	2	-	-	-	⊖=0° ⊕=0°	3
Response Time(rise)	Tr	<b>25</b> ℃	-	-	250	ms	⊖=0° ⊕=0°	4
Response Time(fall)	Tf	<b>25</b> ℃	-	-	250	ms	⊖=0° ⊕=0°	4

## 5. ELECTRO – OPTICAL CHARACTERISTICS



## 6. TERMINAL PIN FUNCTION AND BLOCK DIAGRAM

6-1. Interface Pin Function Description

Pin No.	Symbol	Functions
1	V <sub>DD</sub>	Power for logic
2	SCLK	Serial clock
3	SDIN	Serial data
4	D/C	Select register (H = Data, L = Common)
5	SCE	Chip select (L = Enable)
6	OSC	External clock (H = Internal clock)
7	V <sub>SS</sub>	Ground
8	V <sub>OUT</sub>	LCD output voltage
9	TST2	

#### 6-2. Block Diagram



Cext =min 1.0uF

Higher capacitor values are recommended for ripple reduction.

MODEL GG0804A1FSN6G 6/18 PR	DUCT SPECIFICATIONS REV: A
-----------------------------	----------------------------

#### 7.AC CHARACTERISTICS

#### 7-1 Serial interface



#### 7.AC CHARACTERISTICS (Continued)

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
fosc	oscillator frequency		20	34	65	kнz
fclk(EXT)	external clock frequency		10	32	100	kнz
ffiame	frame frequency	fose or Felkærn=32knz		67		Hz
fvhrl	VDD to RES LOW	Fig.16	0		30	ms
twl(xes)	RES LOW pulse width	Fig.16	100			ns

Serial bus timing characteristics

fsclk	clock frequency	VDD=3.0V±10%	0	 4	MHz
Тсу	clock cycle SCLK	ALL signal timing is based	250		ns
twH1	SCLK pulse width HIGH	on 20% to 80% of VDD	100		ns
tWL1	SCLK pulse width LOW	and maximum rise and fall	100	 	ns
tSU2	SCE set-up time	times of 10 ns	60		ns
th2	SCE hold time		100		ns
twn2	SCE min.HIGH time		100		ns
th5	SCE start hold time;note3		100		ns
tsu3	D/C set-up time		100		ns
th3	D/C hold time		100		ns
tsu4	SDIN set-up		100	 	ns
th4	SDIN hold time		100	 	ns

NOTES:

- 1. Tframe=fclk(ext)/480
- 2. RES may be LOW before VDD goes HIGH.
- 3. Th5 is the time from the previous SCLK positive edge (irrespective of the state of SCE) to the negative edge of SCE (see Fig. 15).

MODEL	GG0804A1FSN6G	8/18	PRODUCT SPECIFICATIONS	REV: A



#### **8.INSTRUCTION DESCRIPTION**

8-1. Table 1 Instruction set

				CO	MMA	ND B	/TE			DESCRIPTION
INSTRUCTION	D/C	B7	<b>B6</b>	B5	B4	<b>B</b> 3	B2	B1	B0	DESCRIPTION
(H = 0 or 1)				•				•		
NOP	0	0	0	0	0	0	0	0	0	No operation
Function set	0	0	0	1	0	0	PD	v	н	Power-down control; entry mode; extended instruction set control (H)
Write data	1	D <sub>7</sub>	D <sub>6</sub>	D <sub>5</sub>	D <sub>4</sub>	D <sub>3</sub>	D <sub>2</sub>	D <sub>1</sub>	D <sub>0</sub>	Writes data to RAM
(H =0)	•			•				•		
Reserved	0	0	0	0	0	0	1	Х	Х	Do not use
Display control	0	0	0	0	0	1	D	0	Е	Sets display configuration
Reserved	0	0	0	0	1	Х	Х	Х	Х	Do not use
Set Y address of RAM	0	0	1	0	0	0	Y <sub>2</sub>	<b>Y</b> <sub>1</sub>	Y <sub>0</sub>	Sets Y- address of RAM: $0 \le Y \le 5$
Set X address of RAM	0	1	X <sub>6</sub>	X <sub>5</sub>	X <sub>4</sub>	X <sub>3</sub>	X <sub>2</sub>	<b>X</b> <sub>1</sub>	X <sub>0</sub>	Sets X-address part of RAM: $0 \le X \le 83$
(H =1)	1									
Reserved	0	0	0	0	0	0	0	0	1	Do not use
	0	0	0	0	0	0	0	1	Х	Do not use
Temperature control	0	0	0	0	0	0	1	TC <sub>1</sub>	TC <sub>0</sub>	Set temperature coefficient (TC <sub>x</sub> )
Reserved	0	0	0	0	0	1	Х	Х	Х	Do not use
Bias system	0	0	0	0	1	0	$BS_2$	$BS_1$	$BS_0$	Set bias system (BS <sub>x</sub> )
Reserved	0	0	1	Х	Х	Х	Х	Х	Х	Do not use
Set V <sub>OP</sub>	0	1	$V_{\text{OP6}}$	$V_{\text{OP5}}$	$V_{\text{OP4}}$	$V_{\text{OP3}}$	$V_{\text{OP2}}$	$V_{\text{OP1}}$	$V_{\text{OP0}}$	Write V <sub>OP</sub> to register
8-2. <b>Table 2</b> Ex	xplanat	tions	of sym	bols i	n Tabl	e 1				
BIT				0						1
PD	Chip	is acti	ve					Chip	is in F	ower-down mode
V	Horiz	ontal	addres	ssing				Vertic	cal ado	dressing
Н	Use basic instruction set					Use e	extenc	led instruction set		
$ \begin{array}{c c} D \text{ and } E \\ 00 \\ 10 \\ 00 \\ 01 \\ 11 \\ I \\ I \\ O \\ O \\ I \\ O \\ I \\ I \\ O \\ I \\ $				n icient icient	0					
MODEL	10     V <sub>LCD</sub> temperature coefficient 2       11     V <sub>LCD</sub> temperature coefficient 3									



## 9. QUALITY SPECIFICATIONS (Continued)

9-3. Sampling Plan and Acceptance

## 1.Sampling Plan

MIL - STD - 105E (  $\parallel$  ) ordinary single inspection is used.

#### 2. Acceptance

Major defect:	AQL = 0.25%
Minor defect:	AQL = 0.65%

#### 9-4. Criteria

#### 1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

#### 2.SMT

Defe	ect	Inspectio	n Item		Inspection Standa	ards
Min	or	Component marking not readable				Reject
Min	or	Component height			Exceed the dimension Of drawing	Reject
Maj	or	Component solder defe wrong component or w	ect (miss rong orie	ing , extra, entation		Reject
Min	or	Component position shift x component soldering pad y $y$ $y$ $y$ $y$ $y$ $y$ $y$ $y$ $y$			X < 3/4Z Y > 1/3D	Reject Reject
Min	or	Component tilt component p soldering pad			Y > 1/3D	Reject
Min	or	Insufficient solder component PAD PCB			<i>θ</i> ≤ 20°	Reject
MODEL		GG0804A1FSN6G	11/18	PRODU	ICT SPECIFICATIONS	REV:

## 9. QUALITY SECIFICATIONS (Continued)

9-4. Criteria (Continued)

#### 3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards				
Major	Crack / breakage	Any	/where	Reject		
		W	L	Acceptable of Scratch		
		w<0.1mm	Any	Ignore		
		0.1 <u>&lt;</u> w<0.2mm	L <u>&lt;</u> 5.0mm	2		
Minor	Frame Scratch	0.2 <u>&lt;</u> w<0.3mm	L <u>&lt;</u> 3.0mm	1		
_		w <u>&gt;</u> 0.3mm	Any	0		
		Note : 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored				
			-	Acceptable of Dents / Pricks		
	Frame Dent , Prick	⊕ <u>&lt;</u> 1.0mm		2		
		1.0<⊕ <u>&lt;</u> 1.5mm		1		
Minor	$\Phi = \frac{L + W}{2}$	1.5mm<⊕		0		
	2	Note : 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (no visible) can be ignored				
Minor	Frame Deformation	Excee	d the dimension of	drawing		
Minor	Metal Frame Oxidation		Any rust			

#### 4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standa	rds
Minor	Tilted soldering	Within the angle $+5^{\circ}$	Acceptable
Minor	Uneven solder joint /bump		Reject
Minor	Minor Hole $\Phi = \frac{L + W}{2}$	Expose the conductive line	Reject
IVIITIOI		Hole $\Psi = \frac{1}{2}$	$\Phi$ > 1.0mm
Minor	Position shift $\gamma^{-\frac{1}{2}}$	Y > 1/3D	Reject
Minor Transform	X > 1/2Z	Reject	

MODEL	GG0804A1FSN6G	12/18	PRODUCT SPECIFICATIONS	REV: A
-------	---------------	-------	------------------------	--------

## 9. QUALITY SPECIFICATIONS (Continued)

9-4. Criteria (Continued)

5. Screw

Defect	Inspection Item	Inspection Standards		
Major	Screw missing/loosen		Reject	
Minor	Screw oxidation	Any rust	Reject	
Minor	Screw deformation	Difficult to accept screw driver	Reject	

6. Heatseal 🚿 TCP 🚿 FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	<b>⊕&gt; 0.5mm</b>	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift $Y \xrightarrow{-\frac{1}{2}} \xrightarrow{-\frac{1}{2}$	Y > 1/3D	Reject
		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards					
	LED dirty, prick	Acceptable number of units					
		⊕ <u>&lt;</u> 0.10mm	Ignore				
		0.10<⊕ <u>&lt;</u> 0.15mm	2				
Minor		0.15<⊕ <u>&lt;</u> 0.2mm	1				
		<b>⊕&gt;0.2mm</b>	0				
		The distance between any two spots should be $\geq$ Any spot/dot/void outside of viewing area is acce	5mm otable				
Minor	Protective film tilt	Not fully cover LCD	Reject				
Major	COG coating	Not fully cover ITO circuit	Reject				

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

## 9. QUALITY SPECIFICATIONS (Continued)

9-4. Criteria (Continued)

9. Inspection Specification of LCD

	* Glass Scrat		1.4.1	Inspection Standards							
		tch !	VV		W<	0.03	0.	03 <w<u>&lt;0.0</w<u>	5 V	V>0.05	
		cratch	L		L	<5		L<3		Any	
Linear Defect	* Fiber and Linear	inear	ACC. NO.		1 L is the length and W			1		Reject	
	material		Note	L is the			V is th	ne width of	the de	efect	
	* Foreign ma	iterial	Φ	⊕ <u>&lt;</u> 0	).1	0.1<⊕ <u>&lt;</u> 0	).15	0.15<⊕ <u>&lt;</u> 0	.2	<b>⊕&gt;0.2</b>	
Black Spot and	between glass polarizer or gla	s and ass	ACC. NO.	3EA 100m	./ im²	2		1		0	
Polarizer Pricked	and glass * Polarizer ho protuberance external force	ole or by	Note	$\Phi$ is the average diameter of the defect. Distance between two defects > 10mm.							
	* Unobvious		Φ		⊕ <u>&lt;</u> (	0.3	0.3	<Φ <u>&lt;</u> 0.5	0.	<b>5&lt;</b> Φ	
White Spot	transparant for material betwe	reign een	ACC. NO.	3EA	./ 10	00mm <sup>2</sup>		1		0	
linor and Bubble in polarizer glass and glass # Air protube between pola		ss or arizer rance izer	Note	$\Phi$ is the average diameter of the defect. Distance between two defects > 10mm.			efect. nm.				
			Φ	⊕ <u>&lt;</u> 0.′	10	0.10<⊕ <u>&lt;</u>	<u>&lt;</u> 0.20	0.20<⊕ <u>&lt;</u>	<u>&lt;</u> 0.25	<b>⊕&gt;0.2</b>	
Segment Defect			ACC. NO.	3EA / 2 1		0					
	Segment		W is more than 1/2 segment width Reje			Reject					
			Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm							
Protuberant Segment			Φ	Φ <u>&lt;</u> 0.1	10	0.10<⊕ <u>&lt;</u>	<u>&lt;</u> 0.20	0.20<⊕ <u>&lt;</u>	<u>&lt;</u> 0.25	<b>⊕&gt;0.2</b>	
	Protuberant Segment		W	W	Glue	Э	W <u>&lt;</u> 1/2 : W <u>&lt;</u> 0.	Seg 2	W <u>&lt;</u> 1/2 W <u>&lt;</u> 0	Seg 2	Ignore
	Φ = ( L + W ) /	2	ACC. NO.	3EA 100mi	/ m²	2		1		0	
			1. Seg	ment							
Assembly Mis-alignment	nor Assembly Mis-alignment		E	3	В <u>&lt;</u>	0.4mm	0.4<	3 <u>&lt;</u> 1.0mm	B>′	1.0mm	
		-	B-	B-A B-A<1/2B		B-	B-A<0.2 B-A<		<0.25		
		A	Jud	dge Acceptable Acceptable Acceptal		eptable					
		₽	2. Dot	ot Matrix			1				
			Defo	Deformation>2° Reje					Reject		
Stain on LCD Panel Surface		1	Accept or a १ above	t when similar items: '	stai one "Bla	ns can be e. Otherw ck spot" a	wipe ise, j nd "W	ed lightly w udged aco /hite Spot"	ith a s cording	soft clot g to th	
	Black Spot and Polarizer Pricked White Spot and Bubble in polarizer Segment Defect Protuberant Segment Assembly Mis-alignment Stain on LCD Panel Surface	Black Spot and Polarizer Pricked* Foreign ma between glass polarizer or gla and glass * Polarizer ho protuberance external forceWhite Spot and Bubble in polarizer* Unobvious transparant fo material betwe glass and glas glass and pola * Air protube between polar and glassSegment DefectImage: Comparison of the system with the system glass and pola * Air protube between polar and glassProtuberant Segment DefectImage: Comparison of the system with the system of the system the system of the system of the system of the system of the system of the system of the system the system the system of the system the system of the sy	Black Spot and Polarizer Pricked* Foreign material between glass and polarizer or glass and glass * Polarizer hole or protuberance by external forceWhite Spot and Bubble in polarizer* Unobvious transparant foreign material between glass and glass or glass and polarizer * Air protuberance between polarizer and glassSegment Defect $\checkmark$ $\psi$ <	Black Spot and Polarizer Pricked       * Foreign material between glass and polarizer or glass and glass * Polarizer hole or protuberance by external force       MO.         White Spot and Bubble in polarizer       * Unobvious transparant foreign material between glass and glass or glass and polarizer * Air protuberance between polarizer and glass       \$	*       Foreign material between glass and polarizer or glass and glass $\Phi \leq 0$ Polarizer       *       Polarizer nole or protuberance by external force $\Phi$ is the distance of the	Black Spot and Polarizer Pricked $*$ Foreign material between glass and polarizer or glass and glass $*$ Polarizer hole or protuberance by external force $\Phi$ is the a Distance b $\Phi$ is the a Distance bWhite Spot and Bubble in polarizer $*$ Unobvious transparant foreign material between glass and glass or glass and polarizer $*$ Air protuberance between polarizer and glass $\Phi$ $\Phi \leq 1$ $ACC$ .White Spot and Bubble in polarizer $*$ Unobvious transparant foreign material between glass and polarizer $*$ Air protuberance between polarizer and glass $\Phi$ $\Phi \leq 0.10$ $ACC$ .Segment Defect $\Psi$ $\Psi = (1 + W)/2$ $\Phi$ $\Phi \leq 0.10$ $ACC$ .Protuberant Segment $\Psi = (1 + W)/2$ $\Psi$ $\Phi \leq 0.10$ $W$ GlueProtuberant Segment $\Psi = (1 + W)/2$ $\Phi$ $\Phi \leq 0.10$ $W$ GlueAssembly Mis-alignment $\Psi = (1 + W)/2$ $B$ B $\Phi = A$ $B A$ $B A$ Assembly Panel Surface $A$ Ccept when stai or a similar one above items: "Bla	*Foreign material between glass and polarizer or glass and glass * Polarizer hole or protuberance by external force $\Phi \leq 0.1$ $0.1 < \Phi \leq 0.1$ White Spot and Bubble in polarizer*Polarizer hole or protuberance by external force $\Phi$ is the average di Distance between twWhite Spot and Bubble in polarizer*Unobvious transparant foreign material between glass and polarizer * $\Phi \leq 0.3$ White Spot and Bubble in polarizer*Unobvious transparant foreign material between glass and polarizer * $\Phi \leq 0.10$ Segment Defect $\Psi$ $\Phi \leq 0.10$ $0.10 < \Phi \leq 0.10$ Vertice $\Psi$ $\Phi \leq 0.10$ $0.10 < \Phi \leq 0.10$ Note $\Psi = 1 + W$ $U = 1 + W$ Distance between twProtuberant Segment $\Psi = (L + W)/2$ $W$ is more than $1/2$ sAssembly Mis-alignment $\Psi = (L + W)/2$ $\Psi = 0.10$ $0.10 < \Phi \leq 0.10$ Assembly Mis-alignment $\Psi = (L + W)/2$ $W$ $B = 0.4 mm$ Assembly Mis-alignment $\Psi = 1.2 m$ $\Psi = 1.2 m$ $B = 0.4 mm$ Stain on LCD Panel Surface $Accept$ when stains can be or a similar one. Otherw above items: "Black spot" a	* Foreign material between glass and polarizer Pricked $\bullet$ Foreign material between glass and polarizer or glass and glass * Polarizer hole or protuberance by external force $\phi$ is the average diameter Distance between two def $\phi$ is the average diameter Distance between two def $\phi$ is the average diameter $\phi$ is the averag	*Foreign material between glass and polarizer or glass and glass * $\Phi$ $\Phi \le 0.1$ $0.1 \le \Phi \le 0.15$ $0.15 \le \Phi \le 0$ Polarizer Prickedpolarizer or glass and glass *Polarizer hole or protuberance by external forceNote $\Phi$ is the average diameter of the de Distance between two defects > 10nWhite Spot and Bubble in polarizer*Unobvious glass and glass or glass and polarizer * $\Phi$ $\Phi \le 0.3$ $0.3 < \Phi \le 0.5$ White Spot and Bubble in polarizer*Unobvious glass and polarizer * $\Phi$ $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.20$ Segment Defect $\Psi$ $\Psi$ $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.20$ $0.20 < \Phi \le 0.20$ Protuberant Segment Defect $\Psi$ $\Psi$ $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.20$ Protuberant Segment Defect $\Psi$ $\Psi$ $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.20$ Protuberant Segment De = (L+W)/2 $\Psi$ $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.20$ WGlue W Glue $W \le 1/2$ Seg $W \le 1/2$ W $S = 0.20$ $W \le 0.20$ Mis-alignment $\Psi$ $\Phi$ $\Phi = A = A < 1/2B$ $B = A < 0.2$ Assembly Mis-alignment $H$ $H$ $H$ $H$ $H$ Assembly Mis-alignment $H$ $H$ $H$ $H$ $H$ Assembly Mis-alignment $H$ $H$ $H$ $H$ $H$ Assembly Panel Surface $H$ $H$ $H$	* Foreign material between glass and polarizer Pricked $\Phi$ $\Phi \leq 0.1$ $0.1 < \Phi \leq 0.15$ $0.15 < \Phi \leq 0.2$ Black Spot and polarizer Prickedpolarizer or glass and glass * Polarizer hole or protuberance by external force $ACC.$ $3EA / 12$ 1White Spot and Bubble in polarizer* Unobvious transparant foreign material between glass and plass or glass and plasizer * Air protuberance between polarizer and glass $\Phi \leq 0.3$ $0.3 < \Phi \leq 0.5$ $0.4$ White Spot and Bubble in polarizer* Unobvious transparant foreign material between glass and plass or glass and plasizer and glass $\Phi \leq 0.3$ $0.3 < \Phi \leq 0.5$ $0.4$ Note $\Phi \leq 0.3$ $0.3 < \Phi \leq 0.5$ $0.4$ $ACC.$ $3EA / 100mm^2$ $1$ Note $\Phi \leq 0.10$ $0.10 < \Phi \leq 0.20$ $0.20 < \Phi \leq 0.20$ $ACC.$ $3EA / 100mm^2$ $1$ Note $\Phi \leq 0.10$ $0.10 < \Phi \leq 0.20$ $0.20 < \Phi \leq 0.25$ $ACC.$ $3EA / 100mm^2$ $1$ Note $\Phi \leq 0.10$ $0.10 < \Phi \leq 0.20$ $0.20 < \Phi \leq 0.25$ $ACC.$ $3EA / 100mm^2$ $1$ Protuberant Segment $\Phi = (1 + W) / 2$ $D$ $D$ $D$ $D$ $D$ $D$ Protuberant Segment $\Phi = (1 + W) / 2$ $D$ $D$ $D$ $D$ $D$ $D$ $D$ $D$ Assembly Mis-alignment $\Phi = (1 + W) / 2$ $D$ Assembly Mis-alignment $\Phi = (1 + W) / 2$	

## **10. RELIABILITY**

NO.	Item	Condition	Criterion
1	High Temperature Operating	<b>70</b> ℃, <b>240Hrs</b>	
2	Low Temperature Operating	-10℃, 240Hrs	
3	High Humidity	80℃, 90%RH, 96Hrs	
4	High Temperature Storage	80℃, 240Hrs	
5	Low Temperature Storage	-30℃, 240Hrs	and operational
		Random wave	
6	Vibration	10 ~ 100Hz	Consumption should
0		Acceleration: 2g	initial value.
		2 Hrs per direction(X,Y,Z)	
	Thermal Shock	-30℃ to 25℃ to 80℃	
7		(60Min) (5Min) (60Min) 10Cycles	
0	ESD Tasting	Contract Discharge Voltage: +1 ~ 5kV and –1 ~ –5kV	There will be discharged ten times
8	ESD lesting	Air Discharge Voltage: +1 ~ 8kV and –1 ~ -8kV	voltage gap is 1kV.
Note	<ul><li>1) Above conditions are su</li><li>2) For restrict products, the</li></ul>	itable for GOLDENTEK stand e test conditions listed as abo	ard products. ve must be revised.

MODEL	GG0804A1FSN6G	15/18	PRODUCT SPECIFICATIONS	REV: A
MODEL	GG0804A1FSN6G	15/18	PRODUCT SPECIFICATIONS	REV: A

## **11. HANDLING PRECAUTIONS**

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloroethane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.

- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
  - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.

MODEL	GG0804A1FSN6G	16/18	PRODUCT SPECIFICATIONS	REV: A
MODEL	GG0804A1FSN6G	16/18	PRODUCT SPECIFICATIONS	REV: A

#### 11. HANDLING PRECAUTIONS (Continued)

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them.

However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance ,for years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
  - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.
  - Which should be burned up later.
  - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

MODEL	GG0804A1FSN6G	17/18	PRODUCT SPECIFICATIONS	REV: A

